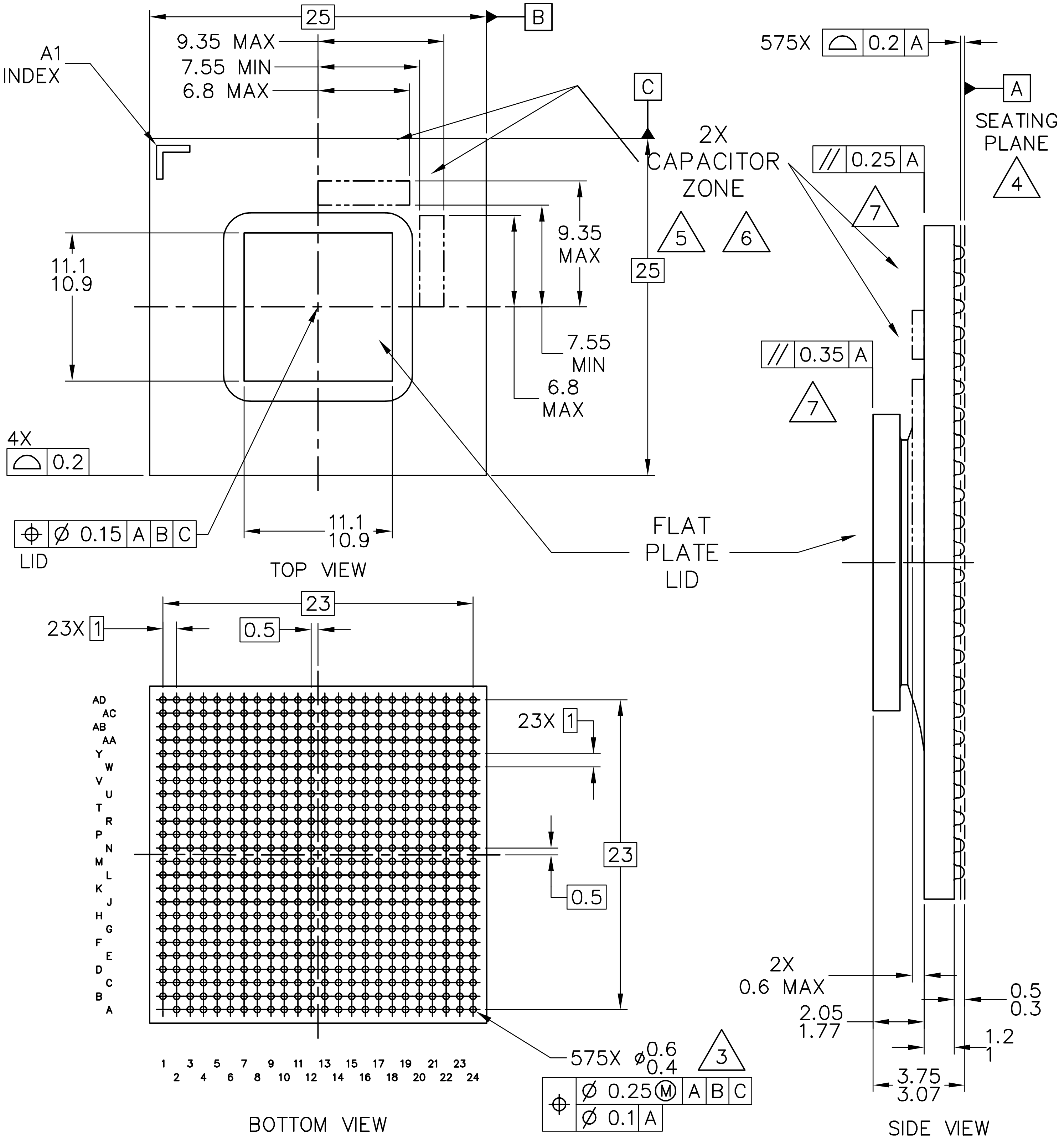

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE:
575 I/O FC PBGA
25 X 25 PKG 1 MM PITCH
WITH FLAT PLATE LID AND CAP ZONES

DOCUMENT NO: 98ARE10543D REV: B

STANDARD: NON–JEDEC

SOT1621–1 17 DEC 2015

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

△3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

△4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

△6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

△7. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

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